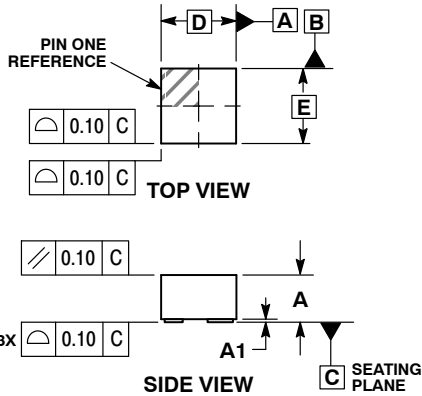




SCALE 8:1

**XLLGA3, 0.62x0.62, 0.35P**  
CASE 713AB  
ISSUE O

DATE 25 SEP 2012



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

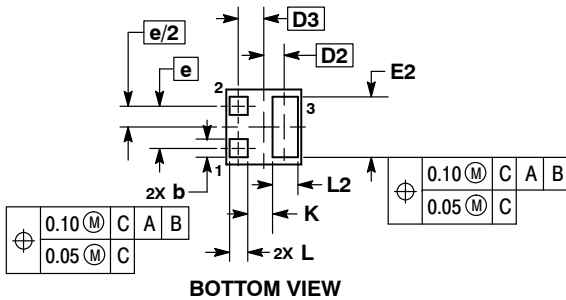
MILLIMETERS		
DIM	MIN	MAX
A	0.340	0.440
A1	0.000	0.030
b	0.100	0.200
D	0.620 BSC	
D2	0.175 BSC	
D3	0.205 BSC	
E	0.620 BSC	
E2	0.400	0.600
e	0.350 BSC	
K	0.200 REF	
L	0.090	0.210
L2	0.110	0.310

**GENERIC MARKING DIAGRAM\***

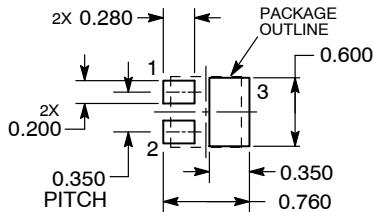


- X = Specific Device Code
- M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.



**RECOMMENDED SOLDER FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

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<b>DESCRIPTION:</b>	<b>XLLGA3, 0.62X0.62, 0.35P</b>	<b>PAGE 1 OF 1</b>

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